



PC Board Layout
Component Side Shown

NOTES:

MATERIAL :

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|--------------------|----------------------------------|
| 1.HOUSING MATERIAL | :GLASS FILLED POLYESTER UL94V-0. |
| 2.CONTACT MATERIAL | :PHOSPHOR BRONZE ϕ 0.46mm. |
| 3.PLATING | :GOLD PLATING OVER NICKEL. |

ELECTRICAL:

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|--------------------------------------|------------------------------|
| 1.VOLTAGE RATING | :125 VAC RMS. |
| 2.CURRENT RATING | :1.5 AMP. |
| 3.CONTACT RESISTANCE | :30 MILLIOHMS MAX. |
| 4.INSULATION RESISTANCE | :500 MEGOHMS MIN @ 500V DC . |
| 5.DIELECTRIC WITHSTANDING RESISTANCE | :1000V AC RMS 50Hz. 1MIN. |

MECHANICAL:

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| 1.DURRABILITY | :750 CYCLES MIN. |
| 2.PCB RETENTION PRE-SOLDER | :1 LB MIN. |

ENVIRONMENTAL:

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|--------------|-------------------------------------|
| 1. STORAGE | : -40 $^{\circ}$ C~+85 $^{\circ}$ C |
| 2. OPERATION | : 0? TO 70?. |



深圳市华宇创精密电子有限公司

TOLERANCE: X.X \pm 0.30 X.XX \pm 0.25 X.XXX \pm 0.15 X.' \pm 2' X.X' \pm 0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: RJ11 90 ° DIP 4P4C
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. : HYCW01-RJ11-100B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO. : HYC-2303141235
			SHEET NO. : 1 OF 1